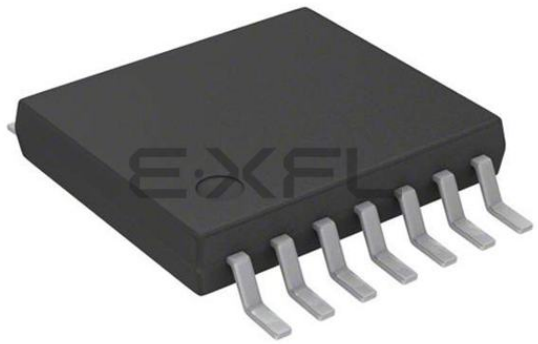

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	14-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	14-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1823-e-st

TABLE 3-3: PIC12(L)F1822/16(L)F1823 MEMORY MAP, BANKS 0-7

	BANK 0		BANK 1		BANK 2		BANK 3		BANK 4		BANK 5		BANK 6		BANK 7	
000h	INDF0	080h	INDF0	100h	INDF0	180h	INDF0	200h	INDF0	280h	INDF0	300h	INDF0	380h	INDF0
001h	INDF1	081h	INDF1	101h	INDF1	181h	INDF1	201h	INDF1	281h	INDF1	301h	INDF1	381h	INDF1
002h	PCL	082h	PCL	102h	PCL	182h	PCL	202h	PCL	282h	PCL	302h	PCL	382h	PCL
003h	STATUS	083h	STATUS	103h	STATUS	183h	STATUS	203h	STATUS	283h	STATUS	303h	STATUS	383h	STATUS
004h	FSR0L	084h	FSR0L	104h	FSR0L	184h	FSR0L	204h	FSR0L	284h	FSR0L	304h	FSR0L	384h	FSR0L
005h	FSR0H	085h	FSR0H	105h	FSR0H	185h	FSR0H	205h	FSR0H	285h	FSR0H	305h	FSR0H	385h	FSR0H
006h	FSR1L	086h	FSR1L	106h	FSR1L	186h	FSR1L	206h	FSR1L	286h	FSR1L	306h	FSR1L	386h	FSR1L
007h	FSR1H	087h	FSR1H	107h	FSR1H	187h	FSR1H	207h	FSR1H	287h	FSR1H	307h	FSR1H	387h	FSR1H
008h	BSR	088h	BSR	108h	BSR	188h	BSR	208h	BSR	288h	BSR	308h	BSR	388h	BSR
009h	WREG	089h	WREG	109h	WREG	189h	WREG	209h	WREG	289h	WREG	309h	WREG	389h	WREG
00Ah	PCLATH	08Ah	PCLATH	10Ah	PCLATH	18Ah	PCLATH	20Ah	PCLATH	28Ah	PCLATH	30Ah	PCLATH	38Ah	PCLATH
00Bh	INTCON	08Bh	INTCON	10Bh	INTCON	18Bh	INTCON	20Bh	INTCON	28Bh	INTCON	30Bh	INTCON	38Bh	INTCON
00Ch	PORTA	08Ch	TRISA	10Ch	LATA	18Ch	ANSELA	20Ch	WPUA	28Ch	—	30Ch	—	38Ch	—
00Dh	—	08Dh	—	10Dh	—	18Dh	—	20Dh	—	28Dh	—	30Dh	—	38Dh	—
00Eh	PORTC(1)	08Eh	TRISC(1)	10Eh	LATC(1)	18Eh	ANSELC(1)	20Eh	WPUC(1)	28Eh	—	30Eh	—	38Eh	—
00Fh	—	08Fh	—	10Fh	—	18Fh	—	20Fh	—	28Fh	—	30Fh	—	38Fh	—
010h	—	090h	—	110h	—	190h	—	210h	—	290h	—	310h	—	390h	—
011h	PIR1	091h	PIE1	111h	CM1CON0	191h	EEADRL	211h	SSP1BUF	291h	CCPR1L	311h	—	391h	IOCAP
012h	PIR2	092h	PIE2	112h	CM1CON1	192h	EEADRH	212h	SSP1ADD	292h	CCPR1H	312h	—	392h	IOCAN
013h	—	093h	—	113h	CM2CON0(1)	193h	EEDATL	213h	SSP1MASK	293h	CCP1CON	313h	—	393h	IOCAF
014h	—	094h	—	114h	CM2CON1(1)	194h	EEDATH	214h	SSP1STAT	294h	PWM1CON	314h	—	394h	—
015h	TMR0	095h	OPTION	115h	CMOUT	195h	EECON1	215h	SSP1CON1	295h	CCP1AS	315h	—	395h	—
016h	TMR1L	096h	PCON	116h	BORCON	196h	EECON2	216h	SSP1CON2	296h	PSTR1CON	316h	—	396h	—
017h	TMR1H	097h	WDTCON	117h	FVRCON	197h	—	217h	SSP1CON3	297h	—	317h	—	397h	—
018h	T1CON	098h	OSCTUNE	118h	DACCON0	198h	—	218h	—	298h	—	318h	—	398h	—
019h	T1GCON	099h	OSCCON	119h	DACCON1	199h	RCREG	219h	—	299h	—	319h	—	399h	—
01Ah	TMR2	09Ah	OSCSTAT	11Ah	SRCON0	19Ah	TXREG	21Ah	—	29Ah	—	31Ah	—	39Ah	CLKRCON
01Bh	PR2	09Bh	ADRESL	11Bh	SRCON1	19Bh	SPBRGL	21Bh	—	29Bh	—	31Bh	—	39Bh	—
01Ch	T2CON	09Ch	ADRESH	11Ch	—	19Ch	SPBRGH	21Ch	—	29Ch	—	31Ch	—	39Ch	MDCON
01Dh	—	09Dh	ADCON0	11Dh	APFCON	19Dh	RCSTA	21Dh	—	29Dh	—	31Dh	—	39Dh	MDSRC
01Eh	CPSCON0	09Eh	ADCON1	11Eh	—	19Eh	TXSTA	21Eh	—	29Eh	—	31Eh	—	39Eh	MDCARL
01Fh	CPSCON1	09Fh	—	11Fh	—	19Fh	BAUDCON	21Fh	—	29Fh	—	31Fh	—	39Fh	MDCARH
020h	General Purpose Register 80 Bytes	0A0h	General Purpose Register 32 Bytes	120h	Unimplemented Read as '0'	1A0h	Unimplemented Read as '0'	220h	Unimplemented Read as '0'	2A0h	Unimplemented Read as '0'	320h	Unimplemented Read as '0'	3A0h	Unimplemented Read as '0'
06Fh		0BFh		16Fh		1EFh		26Fh		2EFh		36Fh		3EFh	
070h	Common RAM	0C0h	Unimplemented Read as '0'	170h	Accesses 70h – 7Fh	1F0h	Accesses 70h – 7Fh	270h	Accesses 70h – 7Fh	2F0h	Accesses 70h – 7Fh	370h	Accesses 70h – 7Fh	3F0h	Accesses 70h – 7Fh
07Fh		0FFh	Accesses 70h – 7Fh	17Fh		1FFh		27Fh		2FFh		37Fh		3FFh	

Legend: = Unimplemented data memory locations, read as '0'.

Note 1: Available only on PIC16(L)F1823.

TABLE 3-8: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 6											
300h(1)	INDF0	Addressing this location uses contents of FSR0H/FSR0L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
301h(1)	INDF1	Addressing this location uses contents of FSR1H/FSR1L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
302h(1)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	0000 0000
303h(1)	STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	---1 1000	---q quuu
304h(1)	FSR0L	Indirect Data Memory Address 0 Low Pointer								0000 0000	uuuu uuuu
305h(1)	FSR0H	Indirect Data Memory Address 0 High Pointer								0000 0000	0000 0000
306h(1)	FSR1L	Indirect Data Memory Address 1 Low Pointer								0000 0000	uuuu uuuu
307h(1)	FSR1H	Indirect Data Memory Address 1 High Pointer								0000 0000	0000 0000
308h(1)	BSR	—	—	—	BSR<4:0>					---0 0000	---0 0000
309h(1)	WREG	Working Register								0000 0000	uuuu uuuu
30Ah(1)	PCLATH	—	Write Buffer for the upper 7 bits of the Program Counter							-000 0000	-000 0000
30Bh(1)	INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	0000 000x	0000 000u
30Ch	—	Unimplemented								—	—
30Dh	—	Unimplemented								—	—
30Eh	—	Unimplemented								—	—
30Fh	—	Unimplemented								—	—
310h	—	Unimplemented								—	—
311h	—	Unimplemented								—	—
312h	—	Unimplemented								—	—
313h	—	Unimplemented								—	—
314h	—	Unimplemented								—	—
315h	—	Unimplemented								—	—
316h	—	Unimplemented								—	—
317h	—	Unimplemented								—	—
318h	—	Unimplemented								—	—
319h	—	Unimplemented								—	—
31Ah	—	Unimplemented								—	—
31Bh	—	Unimplemented								—	—
31Ch	—	Unimplemented								—	—
31Dh	—	Unimplemented								—	—
31Eh	—	Unimplemented								—	—
31Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, r = reserved.
Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: PIC16(L)F1823 only.
3: Unimplemented. Read as '1'.
4: PIC12(L)F1822 only.

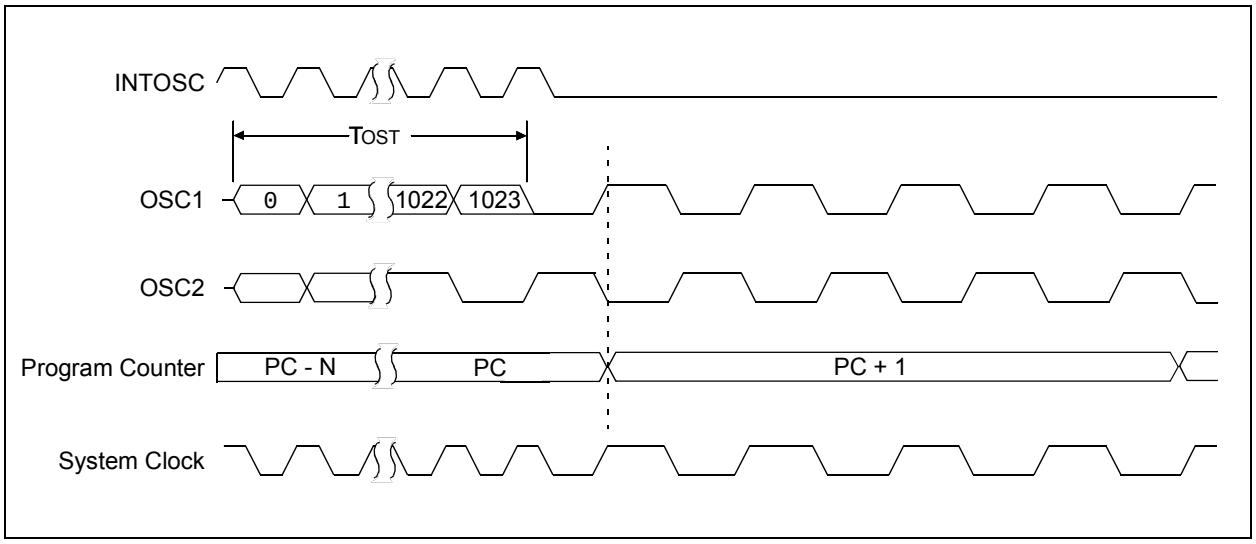
5.4.2 TWO-SPEED START-UP SEQUENCE

1. Wake-up from Power-on Reset or Sleep.
2. Instructions begin execution by the internal oscillator at the frequency set in the IRCF<3:0> bits of the OSCCON register.
3. OST enabled to count 1024 clock cycles.
4. OST timed out, wait for falling edge of the internal oscillator.
5. OSTS is set.
6. System clock held low until the next falling edge of new clock (LP, XT or HS mode).
7. System clock is switched to external clock source.

5.4.3 CHECKING TWO-SPEED CLOCK STATUS

Checking the state of the OSTS bit of the OSCSTAT register will confirm if the microcontroller is running from the external clock source, as defined by the FOSC<2:0> bits in the Configuration Word 1, or the internal oscillator.

FIGURE 5-8: TWO-SPEED START-UP



7.3 MCLR

The MCLR is an optional external input that can reset the device. The MCLR function is controlled by the MCLRE bit of Configuration Word 1 and the LVP bit of Configuration Word 2 (Table 7-2).

TABLE 7-2: MCLR CONFIGURATION

MCLRE	LVP	MCLR
0	0	Disabled
1	0	Enabled
x	1	Enabled

7.3.1 MCLR ENABLED

When MCLR is enabled and the pin is held low, the device is held in Reset. The MCLR pin is connected to VDD through an internal weak pull-up.

The device has a noise filter in the MCLR Reset path. The filter will detect and ignore small pulses.

Note:	A Reset does not drive the MCLR pin low.

7.3.2 MCLR DISABLED

When MCLR is disabled, the pin functions as a general purpose input and the internal weak pull-up is under software control. See **Section 12.2 "PORTA Registers"** for more information.

7.4 Watchdog Timer (WDT) Reset

The Watchdog Timer generates a Reset if the firmware does not issue a CLRWDT instruction within the time-out period. The TO and PD bits in the STATUS register are changed to indicate the WDT Reset. See **Section 10.0 "Watchdog Timer"** for more information.

7.5 RESET Instruction

A RESET instruction will cause a device Reset. The RI bit in the PCON register will be set to '0'. See Table 7-4 for default conditions after a RESET instruction has occurred.

7.6 Stack Overflow/Underflow Reset

The device can reset when the Stack Overflows or Underflows. The STKOVF or STKUNF bits of the PCON register indicate the Reset condition. These Resets are enabled by setting the STVREN bit in Configuration Word 2. See **Section 3.4.2 "Overflow/Underflow Reset"** for more information.

7.7 Programming Mode Exit

Upon exit of Programming mode, the device will behave as if a POR had just occurred.

7.8 Power-Up Timer

The Power-up Timer optionally delays device execution after a BOR or POR event. This timer is typically used to allow VDD to stabilize before allowing the device to start running.

The Power-up Timer is controlled by the PWRTE bit of Configuration Word 1.

7.9 Start-up Sequence

Upon the release of a POR or BOR, the following must occur before the device will begin executing:

1. Power-up Timer runs to completion (if enabled).
2. Oscillator start-up timer runs to completion (if required for oscillator source).
3. MCLR must be released (if enabled).

The total time-out will vary based on oscillator configuration and Power-up Timer configuration. See **Section 5.0 "Oscillator Module (With Fail-Safe Clock Monitor)"** for more information.

The Power-up Timer and oscillator start-up timer run independently of MCLR Reset. If MCLR is kept low long enough, the Power-up Timer and oscillator start-up timer will expire. Upon bringing MCLR high, the device will begin execution immediately (see Figure 7-4). This is useful for testing purposes or to synchronize more than one device operating in parallel.

10.1 Independent Clock Source

The WDT derives its time base from the 31 kHz LFINTOSC internal oscillator.

10.2 WDT Operating Modes

The Watchdog Timer module has four operating modes controlled by the WDTE<1:0> bits in Configuration Word 1. See Table 10-1.

10.2.1 WDT IS ALWAYS ON

When the WDTE bits of Configuration Word 1 are set to '11', the WDT is always on.

WDT protection is active during Sleep.

10.2.2 WDT IS OFF IN SLEEP

When the WDTE bits of Configuration Word 1 are set to '10', the WDT is on, except in Sleep.

WDT protection is not active during Sleep.

10.2.3 WDT CONTROLLED BY SOFTWARE

When the WDTE bits of Configuration Word 1 are set to '01', the WDT is controlled by the SWDTEN bit of the WDTCON register.

WDT protection is unchanged by Sleep. See Table 10-1 for more details.

TABLE 10-1: WDT OPERATING MODES

WDTE Config bits	SWDTEN	Device Mode	WDT Mode
WDT_ON (11)	X	X	Active
WDT_NSLEEP (10)	X	Awake	Active
WDT_NSLEEP (10)	X	Sleep	Disabled
WDT_SWDTEN (01)	1	X	Active
WDT_SWDTEN (01)	0	X	Disabled
WDT_OFF (00)	X	X	Disabled

10.3 Time-Out Period

The WDTPS bits of the WDTCON register set the time-out period from 1 ms to 256 seconds. After a Reset, the default time-out period is two seconds.

10.4 Clearing the WDT

The WDT is cleared when any of the following conditions occur:

- Any Reset
- CLRWDT instruction is executed
- Device enters Sleep
- Device wakes up from Sleep
- Oscillator fail event
- WDT is disabled
- OST is running

See Table 10-2 for more information.

10.5 Operation During Sleep

When the device enters Sleep, the WDT is cleared. If the WDT is enabled during Sleep, the WDT resumes counting.

When the device exits Sleep, the WDT is cleared again. The WDT remains clear until the OST, if enabled, completes. See **Section 5.0 "Oscillator Module (With Fail-Safe Clock Monitor)"** for more information on the OST.

When a WDT time-out occurs while the device is in Sleep, no Reset is generated. Instead, the device wakes up and resumes operation. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register are changed to indicate the event. See **Section 3.0 "Memory Organization"** and The STATUS register (Register 3-1) for more information.

TABLE 10-2: WDT CLEARING CONDITIONS

Conditions	WDT
WDTE<1:0> = 00	Cleared
WDTE<1:0> = 01 and SWDTEN = 0	
WDTE<1:0> = 10 and enter Sleep	
CLRWDT Command	
Oscillator Fail Detected	
Exit Sleep + System Clock = T1OSC, EXTRC, INTOSC, EXTCLK	
Exit Sleep + System Clock = XT, HS, LP	Cleared until the end of OST
Change INTOSC divider (IRCF bits)	Unaffected

TABLE 21-5: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER1

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0	118
CCP1CON	P1M1	P1M0	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	213
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	87
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	89
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								169*
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								169*
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	117
T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	173
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/$\overline{\text{DONE}}$	T1GVAL	T1GSS1	T1GSS0	174

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the Timer1 module.

* Page provides register information.

Note 1: PIC16(L)F1823 only.

24.3.5 PWM RESOLUTION

The resolution determines the number of available duty cycles for a given period. For example, a 10-bit resolution will result in 1024 discrete duty cycles, whereas an 8-bit resolution will result in 256 discrete duty cycles.

The maximum PWM resolution is 10 bits when PR2 is 255. The resolution is a function of the PR2 register value as shown by Equation 24-4.

EQUATION 24-4: PWM RESOLUTION

$$Resolution = \frac{log[4(PR2 + 1)]}{log(2)} \ bits$$

Note: If the pulse width value is greater than the period the assigned PWM pin(s) will remain unchanged.

TABLE 24-5: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (FOSC = 32 MHz)

PWM Frequency	1.95 kHz	7.81 kHz	31.25 kHz	125 kHz	250 kHz	333.3 kHz
Timer Prescale (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	6.6

TABLE 24-6: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (FOSC = 20 MHz)

PWM Frequency	1.22 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescale (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	6.6

TABLE 24-7: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (FOSC = 8 MHz)

PWM Frequency	1.22 kHz	4.90 kHz	19.61 kHz	76.92 kHz	153.85 kHz	200.0 kHz
Timer Prescale (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0x65	0x65	0x65	0x19	0x0C	0x09
Maximum Resolution (bits)	8	8	8	6	5	5

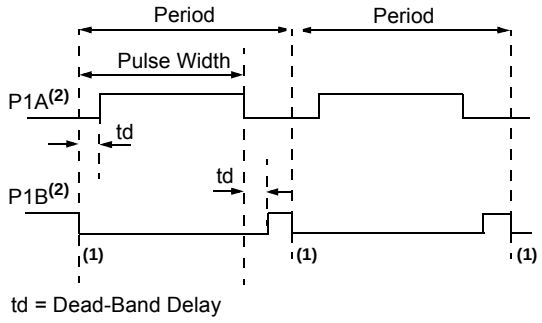
24.4.1 HALF-BRIDGE MODE

In Half-Bridge mode, two pins are used as outputs to drive push-pull loads. The PWM output signal is output on the CCP1/P1A pin, while the complementary PWM output signal is output on the P1B pin (see Figure 24-9). This mode can be used for Half-Bridge applications, as shown in Figure 24-9, or for Full-Bridge applications, where four power switches are being modulated with two PWM signals.

In Half-Bridge mode, the programmable dead-band delay can be used to prevent shoot-through current in Half-Bridge power devices. The value of the PDC<6:0> bits of the PWM1CON register sets the number of instruction cycles before the output is driven active. If the value is greater than the duty cycle, the corresponding output remains inactive during the entire cycle. See **Section 24.4.5 "Programmable Dead-Band Delay Mode"** for more details of the dead-band delay operations.

Since the P1A and P1B outputs are multiplexed with the PORT data latches, the associated TRIS bits must be cleared to configure P1A and P1B as outputs.

FIGURE 24-8: EXAMPLE OF HALF-BRIDGE PWM OUTPUT

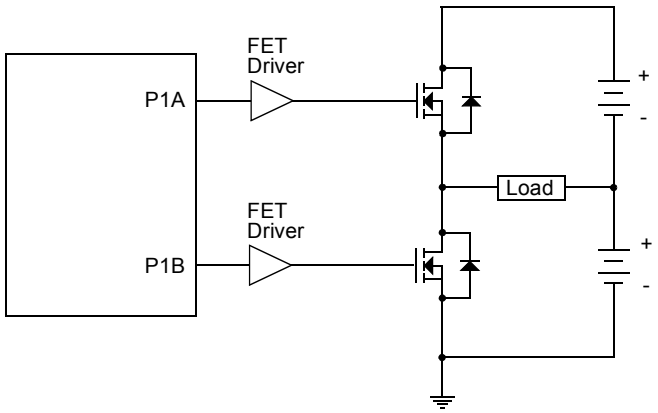


Note 1: At this time, the TMR2 register is equal to the PR2 register.

2: Output signals are shown as active-high.

FIGURE 24-9: EXAMPLE OF HALF-BRIDGE APPLICATIONS

Standard Half-Bridge Circuit ("Push-Pull")



Half-Bridge Output Driving a Full-Bridge Circuit

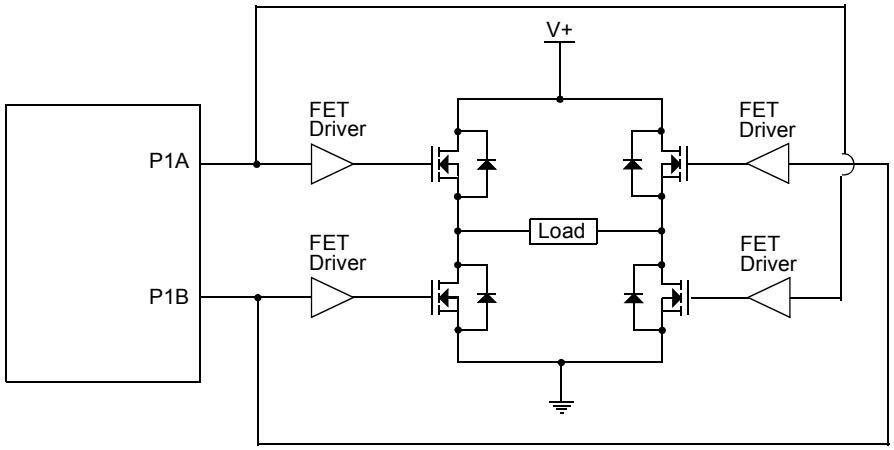
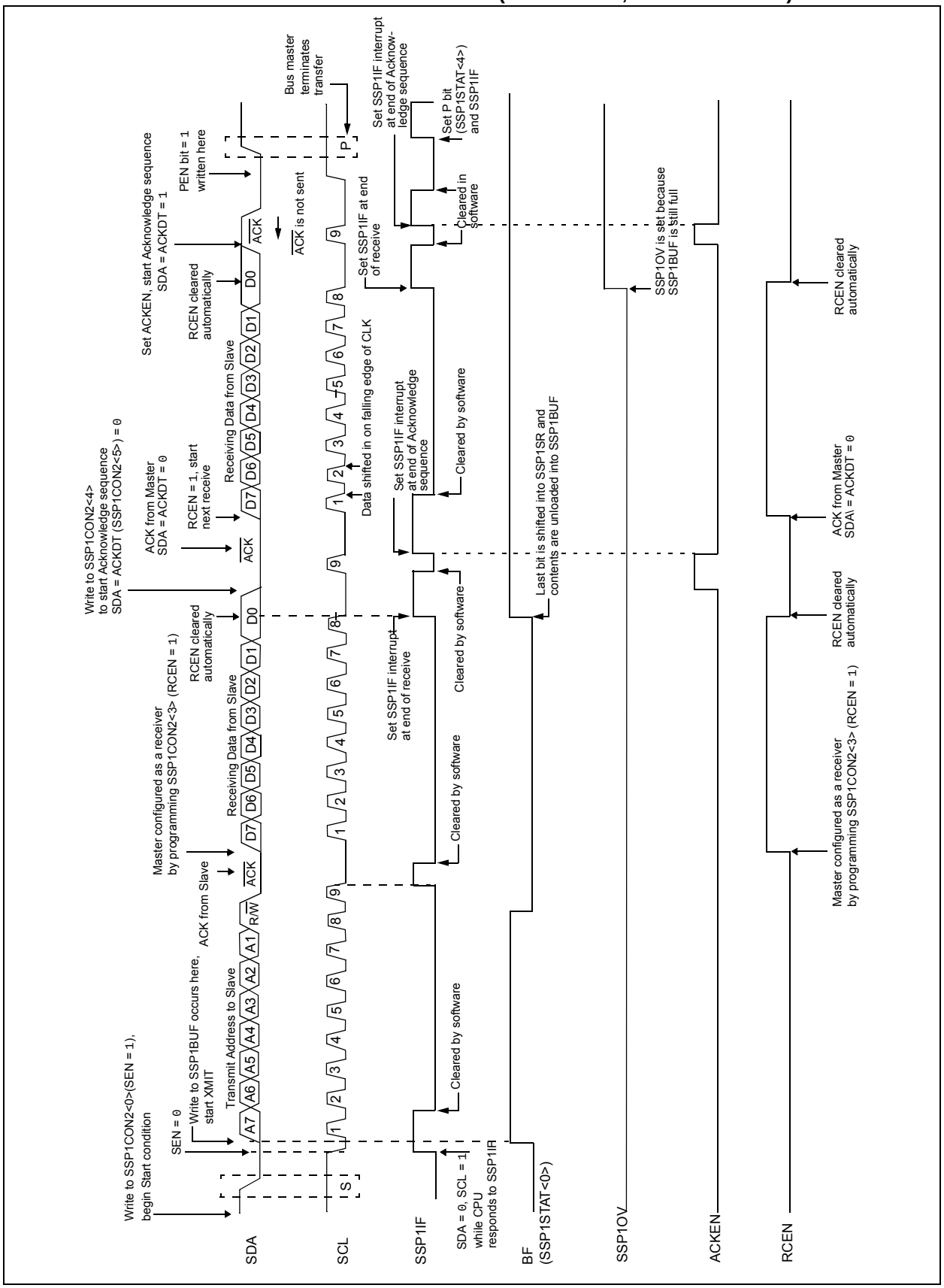


FIGURE 25-29: I²C MASTER MODE WAVEFORM (RECEPTION, 7-BIT ADDRESS)



25.6.13.3 Bus Collision During a Stop Condition

Bus collision occurs during a Stop condition if:

a) After the SDA pin has been deasserted and allowed to float high, SDA is sampled low after the BRG has timed out (Case 1).

b) After the SCL pin is deasserted, SCL is sampled low before SDA goes high (Case 2).

The Stop condition begins with SDA asserted low. When SDA is sampled low, the SCL pin is allowed to float. When the pin is sampled high (clock arbitration), the Baud Rate Generator is loaded with SSP1ADD and counts down to 0. After the BRG times out, SDA is sampled. If SDA is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0' (Figure 25-38). If the SCL pin is sampled low before SDA is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 25-39).

FIGURE 25-38: BUS COLLISION DURING A STOP CONDITION (CASE 1)

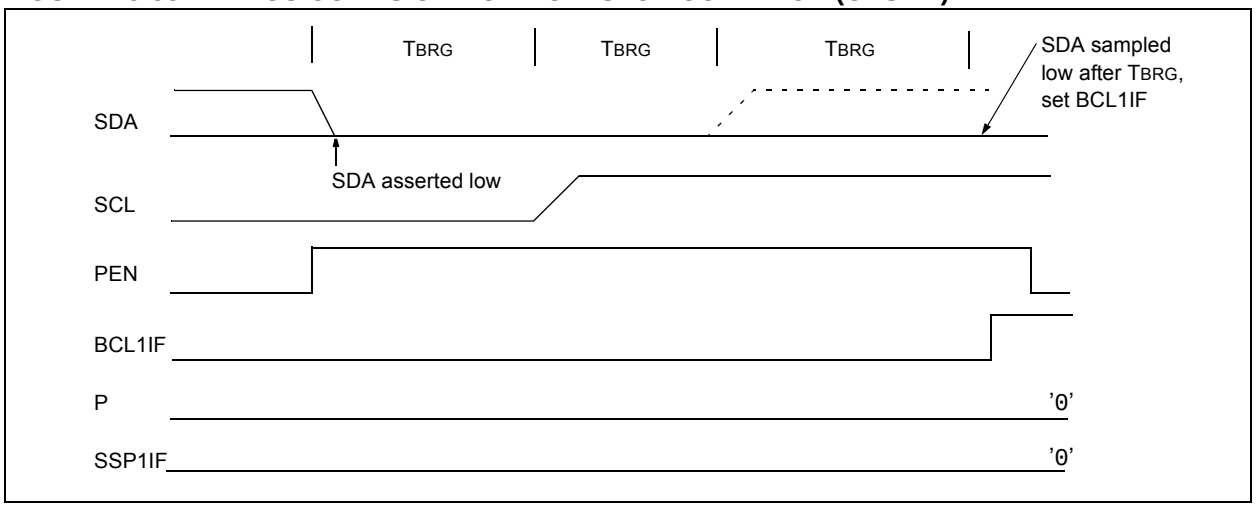
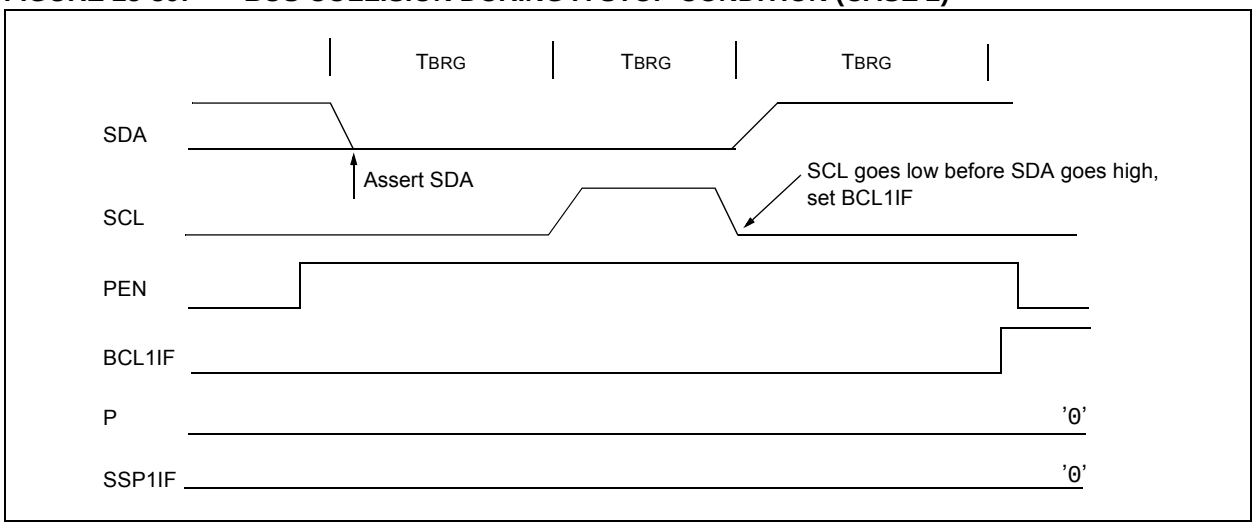


FIGURE 25-39: BUS COLLISION DURING A STOP CONDITION (CASE 2)



26.0 ENHANCED UNIVERSAL SYNCHRONOUS ASYNCHRONOUS RECEIVER TRANSMITTER (EUSART)

The Enhanced Universal Synchronous Asynchronous Receiver Transmitter (EUSART) module is a serial I/O communications peripheral. It contains all the clock generators, shift registers and data buffers necessary to perform an input or output serial data transfer independent of device program execution. The EUSART, also known as a Serial Communications Interface (SCI), can be configured as a full-duplex asynchronous system or half-duplex synchronous system. Full-Duplex mode is useful for communications with peripheral systems, such as CRT terminals and personal computers. Half-Duplex Synchronous mode is intended for communications with peripheral devices, such as A/D or D/A integrated circuits, serial EEPROMs or other microcontrollers. These devices typically do not have internal clocks for baud rate generation and require the external clock signal provided by a master synchronous device.

The EUSART module includes the following capabilities:

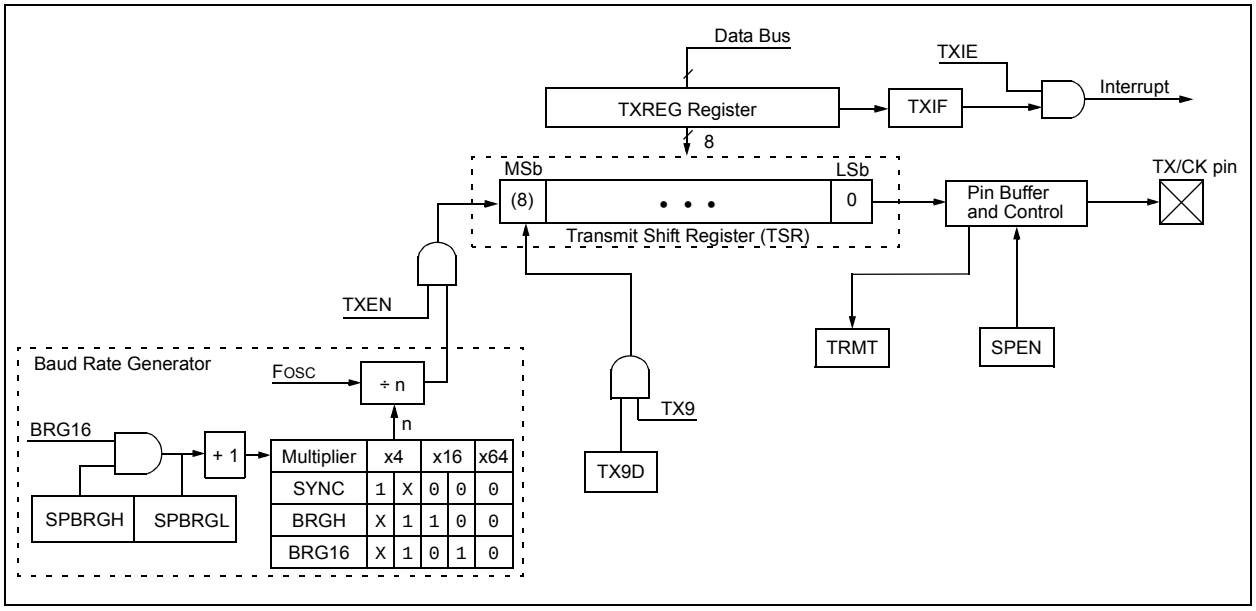
- Full-duplex asynchronous transmit and receive
- Two-character input buffer
- One-character output buffer
- Programmable 8-bit or 9-bit character length
- Address detection in 9-bit mode
- Input buffer overrun error detection
- Received character framing error detection
- Half-duplex synchronous master
- Half-duplex synchronous slave
- Programmable clock polarity in synchronous modes
- Sleep operation

The EUSART module implements the following additional features, making it ideally suited for use in Local Interconnect Network (LIN) bus systems:

- Automatic detection and calibration of the baud rate
- Wake-up on Break reception
- 13-bit Break character transmit

Block diagrams of the EUSART transmitter and receiver are shown in Figure 26-1 and Figure 26-2.

FIGURE 26-1: EUSART TRANSMIT BLOCK DIAGRAM



26.1.2 EUSART ASYNCHRONOUS RECEIVER

The Asynchronous mode is typically used in RS-232 systems. The receiver block diagram is shown in Figure 26-2. The data is received on the RX/DT pin and drives the data recovery block. The data recovery block is actually a high-speed shifter operating at 16 times the baud rate, whereas the serial Receive Shift Register (RSR) operates at the bit rate. When all eight or nine bits of the character have been shifted in, they are immediately transferred to a two character First-In-First-Out (FIFO) memory. The FIFO buffering allows reception of two complete characters and the start of a third character before software must start servicing the EUSART receiver. The FIFO and RSR registers are not directly accessible by software. Access to the received data is via the RCREG register.

26.1.2.1 Enabling the Receiver

The EUSART receiver is enabled for asynchronous operation by configuring the following three control bits:

- CREN = 1
- SYNC = 0
- SPEN = 1

All other EUSART control bits are assumed to be in their default state.

Setting the CREN bit of the RCSTA register enables the receiver circuitry of the EUSART. Clearing the SYNC bit of the TXSTA register configures the EUSART for asynchronous operation. Setting the SPEN bit of the RCSTA register enables the EUSART. The programmer must set the corresponding TRIS bit to configure the RX/DT I/O pin as an input.

Note 1:	If the RX/DT function is on an analog pin, the corresponding ANSEL bit must be cleared for the receiver to function.

26.1.2.2 Receiving Data

The receiver data recovery circuit initiates character reception on the falling edge of the first bit. The first bit, also known as the Start bit, is always a zero. The data recovery circuit counts one-half bit time to the center of the Start bit and verifies that the bit is still a zero. If it is not a zero then the data recovery circuit aborts character reception, without generating an error, and resumes looking for the falling edge of the Start bit. If the Start bit zero verification succeeds then the data recovery circuit counts a full bit time to the center of the next bit. The bit is then sampled by a majority detect circuit and the resulting '0' or '1' is shifted into the RSR. This repeats until all data bits have been sampled and shifted into the RSR. One final bit time is measured and the level sampled. This is the Stop bit, which is always a '1'. If the data recovery circuit samples a '0' in the Stop bit position then a framing error is set for this character, otherwise the framing error is cleared for this character. See **Section 26.1.2.4 "Receive Framing Error"** for more information on framing errors.

Immediately after all data bits and the Stop bit have been received, the character in the RSR is transferred to the EUSART receive FIFO and the RCIF interrupt flag bit of the PIR1 register is set. The top character in the FIFO is transferred out of the FIFO by reading the RCREG register.

Note:	If the receive FIFO is overrun, no additional characters will be received until the overrun condition is cleared. See **Section 26.1.2.5 "Receive Overrun Error"** for more information on overrun errors.

26.1.2.3 Receive Interrupts

The RCIF interrupt flag bit of the PIR1 register is set whenever the EUSART receiver is enabled and there is an unread character in the receive FIFO. The RCIF interrupt flag bit is read-only, it cannot be set or cleared by software.

RCIF interrupts are enabled by setting all of the following bits:

- RCIE interrupt enable bit of the PIE1 register
- PEIE peripheral interrupt enable bit of the INTCON register
- GIE global interrupt enable bit of the INTCON register

The RCIF interrupt flag bit will be set when there is an unread character in the FIFO, regardless of the state of interrupt enable bits.

27.4 Current Ranges

The Capacitive Sensing Oscillator can operate within several different current ranges, depending on the Voltage Reference mode and current range selections. Within each of the two Voltage Reference modes there are four current ranges.

Selection between the Voltage Reference modes is controlled by the CPSRM bit of the CPSCON0 register. Clearing this bit selects the Fixed Voltage References provided by the capacitive sensing oscillator module. Setting this bit selects the variable voltage references supplied by the Fixed Voltage Reference (FVR) module and the Digital-to-Analog Converter (DAC) module. See **Section 27.3 "Voltage References"** for more information on configuring the voltage references. Selecting the current range within the Voltage Reference mode is controlled by configuring the CPSRNG<1:0> bits in the CPSCON0 register. See Table 27-1 for proper current mode selection.

The Noise Detection mode is unique in that it disables the constant-current source associated with the selected input pin, but leaves the rest of the oscillator circuitry and pin structure active. This eliminates the oscillation frequency on the analog pin and greatly reduces the current consumed by the oscillator module. When noise is introduced onto the pin, the oscillator is driven at the frequency determined by the noise. This produces a detectable signal at the comparator stage, indicating the presence of activity on the pin. Figure 27-2 shows a more detailed drawing of the constant-current sources and comparators associated with the oscillator and input pin.

TABLE 27-1: CURRENT MODE SELECTION

CPSRM	Voltage Reference Mode	CPSRNG<1:0>	Current Range(1)
0	Fixed	00	Off
		01	Low
		10	Medium
		11	High
1	Variable	00	Noise Detection
		01	Low
		10	Medium
		11	High

Note 1: See Power-Down Currents (I_{PD}) in **Section 30.3 "DC Characteristics: PIC16(L)F1824/8-I/E (Power-Down)"** for more information.

BCF **Bit Clear f**

Syntax:	[*label*] BCF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	0 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is cleared.

BRA **Relative Branch**

Syntax:	[*label*] BRA label [*label*] BRA $+k
Operands:	-256 ≤ label - PC + 1 ≤ 255 -256 ≤ k ≤ 255
Operation:	(PC) + 1 + k → PC
Status Affected:	None
Description:	Add the signed 9-bit literal 'k' to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 1 + k. This instruction is a 2-cycle instruction. This branch has a limited range.

BRW **Relative Branch with W**

Syntax:	[*label*] BRW
Operands:	None
Operation:	(PC) + (W) → PC
Status Affected:	None
Description:	Add the contents of W (unsigned) to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 1 + (W). This instruction is a 2-cycle instruction.

BSF **Bit Set f**

Syntax:	[*label*] BSF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	1 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

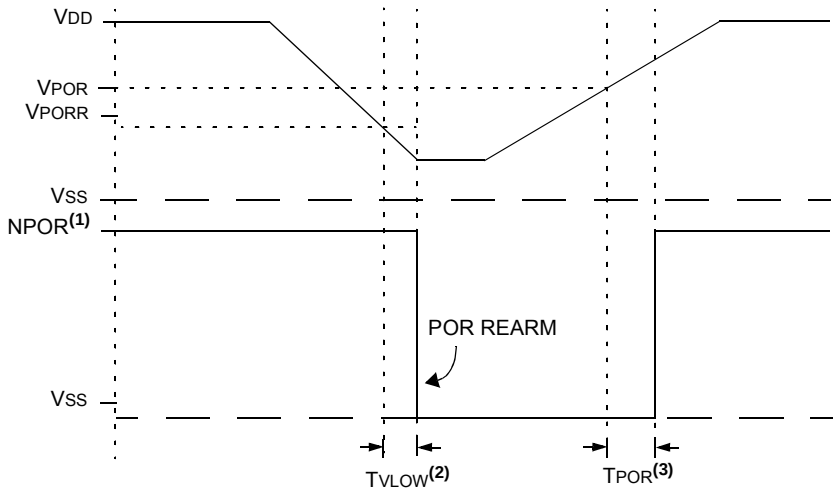
BTFSC **Bit Test f, Skip if Clear**

Syntax:	[*label*] BTFSC f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	skip if (f<b>) = 0
Status Affected:	None
Description:	If bit 'b' in register 'f' is '1', the next instruction is executed. If bit 'b', in register 'f', is '0', the next instruction is discarded, and a NOP is executed instead, making this a 2-cycle instruction.

BTFSS **Bit Test f, Skip if Set**

Syntax:	[*label*] BTFSS f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b < 7
Operation:	skip if (f<b>) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' is '0', the next instruction is executed. If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a 2-cycle instruction.

FIGURE 30-4: POR AND POR REARM WITH SLOW RISING VDD



Note 1: When NPOR is low, the device is held in Reset.
2: TPOR 1 μs typical.
3: TVLOW 2.7 μs typical.

30.2 DC Characteristics: PIC12(L)F1822/16(L)F1823-I/E (Industrial, Extended)

PIC12LF1822/16LF1823			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC12F1822/16F1823			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Device Characteristics**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**	
						VDD	**Note**
	Supply Current (IDD)(1, 2)						
D010		—	5.0	15	µA	1.8	FOSC = 32 kHz, -40°C to +85°C LP Oscillator mode
		—	8.0	19	µA	3.0	
D010		—	24	36	µA	1.8	FOSC = 32 kHz, -40°C to +85°C LP Oscillator mode
		—	30	48	µA	3.0	
		—	32	66	µA	5.0	
D010A		—	5.0	21	µA	1.8	FOSC = 32 kHz, -40°C to +125°C LP Oscillator mode
		—	7.5	25	µA	3.0	
D010A		—	24	60	µA	1.8	FOSC = 32 kHz, -40°C to +125°C LP Oscillator mode
		—	30	70	µA	3.0	
		—	32	80	µA	5.0	
D011		—	60	115	µA	1.8	FOSC = 1 MHz XT Oscillator mode
		—	111	200	µA	3.0	
D011		—	82	135	µA	1.8	FOSC = 1 MHz XT Oscillator mode
		—	141	225	µA	3.0	
		—	200	320	µA	5.0	
D012		—	145	280	µA	1.8	FOSC = 4 MHz XT Oscillator mode
		—	260	460	µA	3.0	
D012		—	165	300	µA	1.8	FOSC = 4 MHz XT Oscillator mode
		—	290	500	µA	3.0	
		—	368	700	µA	5.0	
D013		—	34	170	µA	1.8	FOSC = 1 MHz EC Oscillator mode, Medium-power mode
		—	59	250	µA	3.0	
D013		—	60	200	µA	1.8	FOSC = 1 MHz EC Oscillator mode Medium-power mode
		—	92	260	µA	3.0	
		—	126	350	µA	5.0	
D014		—	118	250	µA	1.8	FOSC = 4 MHz EC Oscillator mode, Medium-power mode
		—	210	420	µA	3.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{MCLR}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: 8 MHz internal RC oscillator with 4x PLL enabled.

4: 8 MHz crystal oscillator with 4x PLL enabled.

5: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ.

30.5 Memory Programming Requirements

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C				
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
		Program Memory High-Voltage Programming Specifications					
D110	VIHH	Voltage on $\overline{\text{MCLR}}$/VPP/RA5 pin	8.0	—	9.0	V	**(Note 3, Note 4)**
D111	IDDVPP	Programming/Erase Current on VPP, High Voltage Programming	—	—	10	mA	
D112	VBE	VDD for Bulk Erase	2.7	—	VDD max.	V	
D113	VPEW	VDD for Write or Row Erase	VDD min.	—	VDD max.	V	
D114	IPPPGM	Programming/Erase Current on VPP, Low Voltage Programming	—	1.0	—	mA	
D115	IDDPGM	Programming/Erase Current on VDD, High or Low Voltage Programming	—	5.0	—	mA	
		Data EEPROM Memory					
D116	ED	Byte Endurance	100K	—	—	E/W	-40°C to +85°C
D117	VDRW	VDD for Read/Write	VDD min.	—	VDD max.	V	
D118	TDEW	Erase/Write Cycle Time	—	4.0	5.0	ms	
D119	TRETD	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated
D120	TREF	Number of Total Erase/Write Cycles before Refresh**(2)**	1M	10M	—	E/W	-40°C to +85°C
		Program Flash Memory					
D121	EP	Cell Endurance	10K	—	—	E/W	-40°C to +85°C (**Note 1**)
D122	VPR	VDD for Read	VDD min.	—	VDD max.	V	
D123	TIW	Self-timed Write Cycle Time	—	2	2.5	ms	
D124	TRETD	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Self-write and Block Erase.

2: Refer to **Section 11.2 "Using the Data EEPROM"** for a more detailed discussion on data EEPROM endurance.

3: Required only if single-supply programming is disabled.

4: The MPLAB ICD 2 does not support variable VPP output. Circuitry to limit the MPLAB ICD 2 VPP voltage must be placed between the MPLAB ICD 2 and target system when programming or debugging with the MPLAB ICD 2.

30.8 AC Characteristics: PIC12(L)F1822/16(L)F1823-I/E

FIGURE 30-6: CLOCK TIMING

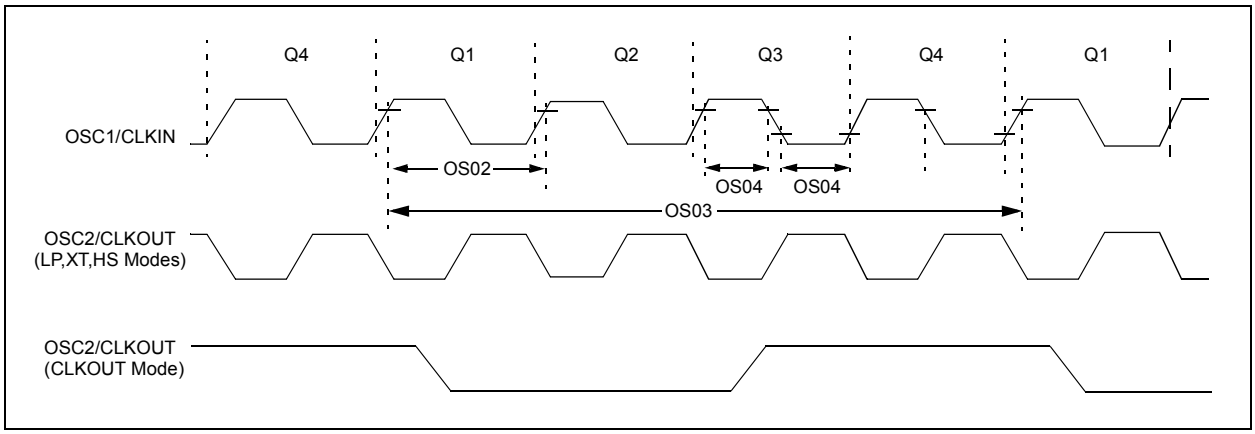


TABLE 30-1: CLOCK OSCILLATOR TIMING REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS01	FOSC	External CLKIN Frequency(1)	DC	—	0.5	MHz	EC Oscillator mode (low)
			DC	—	4	MHz	EC Oscillator mode (medium)
			DC	—	32	MHz	EC Oscillator mode (high)
		Oscillator Frequency(1)	—	32.768	—	kHz	LP Oscillator mode
			0.1	—	4	MHz	XT Oscillator mode
			1	—	4	MHz	HS Oscillator mode, VDD ≤ 2.7V
			1	—	20	MHz	HS Oscillator mode, VDD > 2.7V
			DC	—	4	MHz	RC Oscillator mode
OS02	TOSC	External CLKIN Period(1)	27	—	∞	μs	LP Oscillator mode
			250	—	∞	ns	XT Oscillator mode
			50	—	∞	ns	HS Oscillator mode
			31.25	—	∞	ns	EC Oscillator mode
		Oscillator Period(1)	—	30.5	—	μs	LP Oscillator mode
			250	—	10,000	ns	XT Oscillator mode
			50	—	1,000	ns	HS Oscillator mode
			250	—	—	ns	RC Oscillator mode
OS03	TCY	Instruction Cycle Time(1)	200	—	DC	ns	TCY = FOSC/4
OS04*	TosH, TosL	External CLKIN High, External CLKIN Low	2	—	—	μs	LP oscillator
			100	—	—	ns	XT oscillator
			20	—	—	ns	HS oscillator
OS05*	TosR, TosF	External CLKIN Rise, External CLKIN Fall	0	—	∞	ns	LP oscillator
			0	—	∞	ns	XT oscillator
			0	—	∞	ns	HS oscillator

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

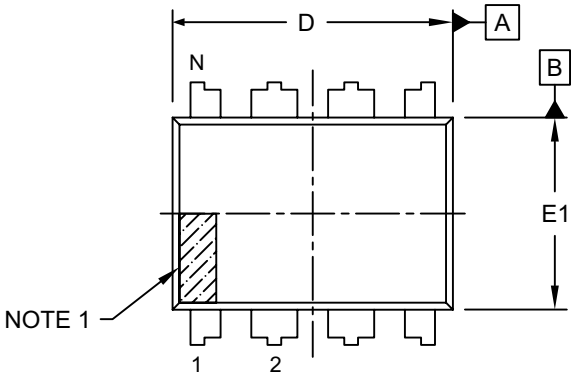
Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

33.2 Package Details

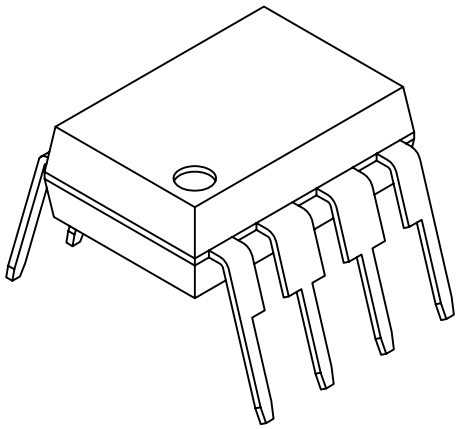
The following sections give the technical details of the packages.

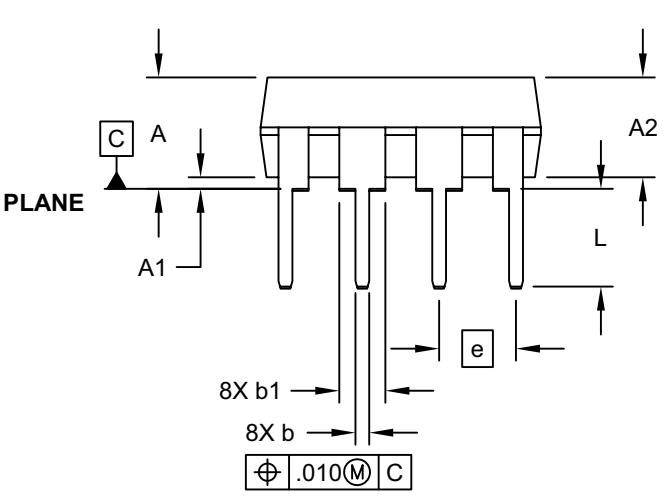
8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

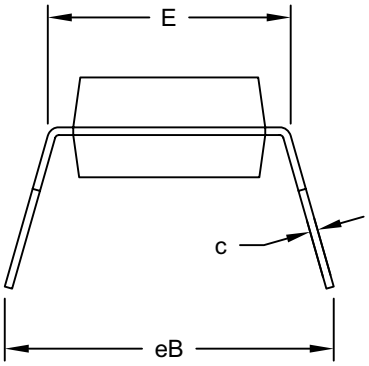


TOP VIEW





SIDE VIEW

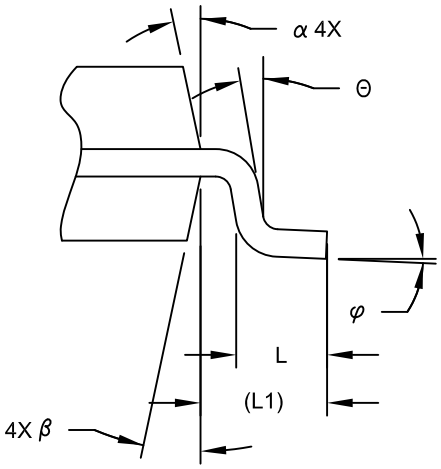


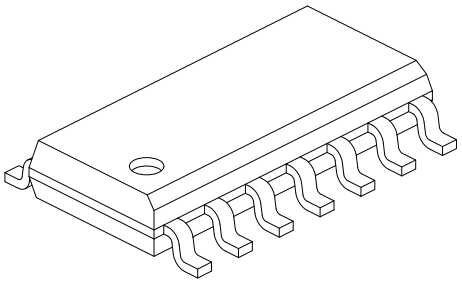
END VIEW

Microchip Technology Drawing No. C04-018D Sheet 1 of 2

14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





VIEW C

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		8.65 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.10	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-065C Sheet 2 of 2